Aurubis Stolberg

Cu-HCP

EN_2026_01

Comparable standards: UNS C10300 • EN CW021A

Aurubis designations: PNA 210 • HCP

Description

Cu-HCP is a deoxidized, oxygen-free copper with a low residual phosphorus content. It combines very good formability, weldability and brazability with high electrical conductivity.

Composition

Cu [%]	P [%]
min 99.95	0.002-0.007

Composition of this alloy is in accordance with RoHS for electric & electronic components and ELV for the automotive industry.

Physical properties

Melting point [°C]	Density [g/cm³]	c_p @ 20°C [kJ/kgK]	Young's modulus [GPa]	Thermal cond. [W/mK]	Electrical cond. [MS/m]	Electrical cond. [%IACS]	α @20-300°C [10^{-6}/K]
1083	8.94	0.377	127	385	≥ 57	≥98	17.7

Note: The specified conductivity applies to the soft condition only.

c_p specific heat capacity

α coefficient of thermal expansion

Mechanical properties

	Tensile Strength [MPa]	Yield Strength [MPa]	Elongation A_{50} [%]	Hardness HV [-]	Bend ratio 90° [r] GW	Bend ratio 90° [r] BW
R220	220-260	≤ 140	≥ 33	40-65	0	0
R240	240-300	≥ 180	≥ 8	65-95	0	0
R290	290-360	≥ 250	≥ 4	90-110	0	0
R360	≥ 360	≥ 320	≥ 2	≥ 110	0	0.5

r = x * t (thickness t ≤ 0.5mm)

GW bend axis transverse to rolling direction. BW bend axis parallel to rolling direction.

Fabrication properties

Cold formability	excellent
Hot formability	excellent
Soldering	excellent
Brazing	excellent
Oxyacetylene welding	fair
Gas shielded arc welding	excellent
Resistance welding	not recommended
Machinability	not recommended

Electrical conductivity

The electrical conductivity depends on chemical composition, the level of cold deformation and the grain size. A high level of deformation as well as a small grain size decrease the conductivity.

Corrosion Resistance

Copper is resistant to: Natural and industrial atmospheres as well as maritime air, drinking and service water, non oxidizing acids, alkaline solutions and neutral saline solutions.
Copper is not resistant to: Ammonia, halogenide, cyanide and hydrogen sulfide solutions and atmospheres, oxidizing acids and sea water (especially at high flow rates).

Typical uses	Telecommunication cables, terminals, clad products, busbars, base plates for power modules, electrical conductors, pressure vessels

This leaflet is for general information only and is not subject to revision. No claims can be derived from it unless there is evidence of intent or gross negligence. The data given are no warranty that the product is of a specified quality and they cannot replace expert advice or the customer's own test.